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For Immediate Release

Promex Showcases Fast-Track Concept-to-Production Electronic Manufacturing Services at MD&M West Expo

Combined IC/SMT Assembly Supported by Deep Engineering Expertise for Complex Medical and Bioscience Products, Plus Quick-Turn Packaging Solutions from Quik-Pak Division

Santa Clara, CA – February 9, 2016 – PRNewswire/iReach – <u>Promex Industries Inc.</u>, a provider of engineering and mixed technology contract electronic manufacturing services, will demonstrate how it fast tracks medical and bioscience products from concept to production in Booth 480 at the <u>Medical Device and Manufacturing West</u> Expo, February 9-11 in Anaheim, Calif. Promex integrates conventional SMT with semiconductor microelectronic packaging and assembly, offering in-house wafer thinning, dicing, wirebond, flip chip surface mount and overmolding services, all of which are supported by an engineering team with more than 35 years of experience with complex assemblies.

"Often medical and bioscience companies come to us with their concept for a Class III implantable or other complex medical device and we help them build up the prototype," said Promex Director of Sales and Marketing Rosie Medina. "Then when they're ready, we help them get their product into production fast utilizing our 30,000-square-foot assembly facility with two RoHS-optimized SMT lines and Class 100 and Class 1000 clean rooms."

Promex features fully controlled process flows for high reliability and is ISO 13485:2003 and ISO 9001:2008 certified, ITAR registered and compliant to regulatory requirements for medical products. The company also offers device designers a time-to-market advantage utilizing the high-throughput, maximum-yield packaging solutions provided by its Quik-Pak Division, a quick-turn prototype specialist for medical devices located in San Diego, Calif.

Quik-Pak's IC packaging solutions for complex RF/MW medical devices include air cavity plastic QFN packages, over-molded plastic QFN/DFN packages, custom transfer molded packaging, and custom assembly for ceramic, laminate, COF and COB. Quik-Pak also offers assembly services from prototype design validation to full production, as well as wafer preparation services including dicing, backgrinding and pick and place. The company's 15,000 square foot facility includes fully automated equipment for high throughput and maximum yield. More information is available at www.icproto.com, or by calling 858-674-4676.

Promex specializes in engineering and proof of concept through production of Class III implantable and other complex medical devices. The company operates a 30,000 square foot assembly facility in Silicon Valley with RoHS-optimized surface mount technology (SMT), Class 100 and 1000 clean rooms and fully controlled process flows for high reliability. Together, the Promex and Quik-Pak facilities are ISO 13485:2003 and ISO 9001:2008 certified, ITAR registered and compliant to regulatory requirements for medical products. More information is available at www.promex-ind.com or by calling 408-496-0222.

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